AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claim 1 (currently amended): A method of producing a thin film circuit board used as a milli-wave or micro-wave module, the method comprising steps of:

cleaning a substrate comprising dielectric ceramic, and having a thickness of 0.05 mm to 2 mm and a flexural strength of 500 kgf/cm^2 to 4000 kgf/cm^2;

forming a conductor film in a predetermined pattern on the substrate, said conductor film including at least one selected from Cu, Au, Ag, Al, Ni, Ti, Cr, Ni-Cr, Nb, and V;

forming an insulating film on the substrate to cover the conductor film, said insulating film comprising at least one organic resin selected from polyimide, epoxy resins, benzocyclobutene resins, acrylic resins, and cyclic olefin resins, and having an area of 5 cm^2 or less per pattern and a stress of 15 MPa to 60 MPa;

curing and patterning the insulating film; and

repeating the insulating film forming step and the insulating film curing and patterning step at least once; wherein

the insulating films have a total thickness of 20 μm or greater.

Claim 2 (currently amended): A method of producing a thin film circuit board according to Claim 1, wherein the insulating film comprises a photosensitive organic film,

said insulating film forming step comprises a step of forming the photosensitive organic film on the substrate, and

said curing and patterning step comprises steps of

exposing and developing the photosensitive organic film by photolithography, and

curing the photosensitive organic film.

Claim 3 (currently amended): A method of producing a thin film circuit board according to Claim 1, wherein the insulating film comprises a non-photosensitive organic film,

said insulating film forming step comprises a step of forming the non-photosensitive organic film on the substrate, and

said curing and patterning step comprises steps of

curing the non-photosensitive organic film,

forming an etching resist on the non-photosensitive organic film,

etching the non-photosensitive organic film by dry etching, and

removing the etching resist.